What is claimed is:

1. An EMI resistant electronics enclosure (200), comprising:

a first compartment (206) defined by a body (205);

a second compartment (207) defined by the body (205);

a septum (208) between the first compartment (206) and the second compartment (207);

a first aperture (209) with the septum (208) that connects the first compartment (206) and the second compartment (207);

a feed-through element (210) comprising a first interface region (211) and a second interface region (212), wherein one or more primary conductors (217) extend between the first interface region (211) and the second interface region (212), and wherein the first interface region (211) resides in the first compartment (206), and the second interface region (212) resides in the second compartment (207);

a conductive bar (232) that circumscribes at least a portion of the feed-through element (210);

a conductive gasket (220) that extends from the body (205) to the conductive bar (232), wherein a ground path is formed between the body (205) and the conductive bar (232) with the conductive gasket (220).

2. The EMI resistant electronics enclosure (200) of claim 1, comprising:

a flexible member (230) comprising secondary internal conductors that are in electrical communication with the primary conductors (217);

an EMI shield (231) formed as an outer layer of the flexible member (230) that surrounds the secondary conductors of the flexible member (230).

3. The EMI resistant electronics enclosure (200) of claim 1, wherein the feed-through element (210) comprises a printed circuit board (PCB).

4. The EMI resistant electronics enclosure (200) of claim 1, wherein the gasket (220) comprises a conductive fabric.

5. The EMI resistant electronics enclosure (200) of claim 2, wherein the EMI shield (231) is in electrical contact with the conductive bar (232).

6. The EMI resistant electronics enclosure (200) of claim 3, wherein the EMI shield (231) is in electrical contact with a secondary PCB (240) disposed in the second compartment (207).

7. The EMI resistant electronics enclosure (200) of claim 6, wherein the secondary PCB (240) comprises a conductive connection point (241), and wherein the conductive connection point (241) is in electrical contact with the EMI shield (231).

8. The EMI resistant electronics enclosure (200) of claim 7, wherein the conductive connection point (241) is grounded.

9. A method of forming an EMI resistant electronics enclosure (200), with the method comprising:

providing a body (205) comprising a first compartment (206) and a second compartment (207);

separating the first compartment (206) and the second compartment (207) with a septum (208);

placing a first aperture (209) in the septum (208) that connects the first compartment (206) and the second compartment (207);

inserting a feed-through element (210) through the first aperture (209) and cavity (225), wherein the feed-through element (210) comprises a first interface region (211) and a second interface region (212), wherein one or more primary conductors (217) extend between the first interface region (211) and the second interface region (212), and wherein the first interface region (211) resides in the first compartment (206), and the second interface region (212) resides in the second compartment (207);

placing a conductive bar (232) around at least a portion of the feed-through element (210); and

installing a conductive gasket (220) between the body (205) and the conductive bar (232), to form a conductive path therebetween.

10. The method of forming an EMI resistant electronics enclosure (200) of claim 9, comprising:

electrically connecting secondary internal conductors of a flexible member (230) to the primary conductors (217); and

surrounding the secondary conductors of the flexible member (230) with an EMI shield (231).

11. The method of forming an EMI resistant electronics enclosure (200) of claim 9, wherein the feed-through element (210) comprises a printed circuit board (PCB).

12. The method of forming an EMI resistant electronics enclosure (200) of claim 9, wherein the gasket (220) comprises a conductive fabric.

13. The method of forming an EMI resistant electronics enclosure (200) of claim 10, comprising the step of placing the EMI shield (231) in electrical contact with the conductive bar (232).

14. The method of forming an EMI resistant electronics enclosure (200) of claim 11, comprising the step of electrically connecting the EMI shield (231) with a secondary PCB (240) disposed in the second compartment (207).

15. The method of forming an EMI resistant electronics enclosure (200) of claim 14, comprising the step of placing a conductive connection point (241) of the secondary PCB (240) in electrical contact with the EMI shield (231).